

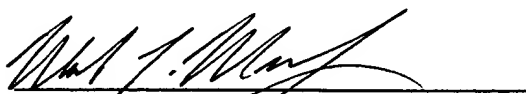


The citation of the above-discussed documents is not to be construed as an assertion that more pertinent art could not possibly be in existence. Citation of any document herein is not to be construed as an admission that any subject matter disclosed in the document is necessarily within the inventive field of endeavor, that any disclosure is necessarily prior in time to a particular date which may be relevant to the instant patent application, and/or that any disclosure is otherwise necessarily prior art with respect to the instant invention.

Applicant also respectfully reserves the right to later set forth how the instant invention is distinguished over the disclosure of any document or other art, including the disclosure of those documents discussed herein, that may be cited by the Examiner in rejecting a claim in the instant patent application.

A first office action, notice of allowance or issue fee notification has been received in this case, so a check in the amount of \$180.00 is enclosed. If any additional fee is required, please charge Deposit Account No. 50/1039.

Respectfully submitted,

  
Mark J. Murphy  
Registration No: 34,225

COOK, ALEX, McFARRON, MANZO,  
CUMMINGS & MEHLER, LTD.  
200 West Adams Street  
Suite 2850  
Chicago, Illinois 60606 (312) 236-8500



LIST OF PUBLICATIONS CITED BY APPLICANT			<u>Atty. Docket No.</u> SEL 245	<u>Serial No.</u> 09/800,627		
			<u>Applicant</u> Koichiro TANAKA et al			
			<u>Filing Date</u> March 7, 2001	<u>Group</u> 2822		
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**OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS**

(Include name of author (in CAPITAL LETTERS), title of article or item (book, magazine, journal, serial, symposium, catalog, etc.) date, pages(s), volume-issue number(s), publisher, city and/or country where published).

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